

**Erratum: “Solder Joint Shape Prediction Using a
Modified Perzyna Viscoplastic Model”
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Mudasir Ahmad, Ken Hubbard, and Mason Hu

Part (c) of Fig. 6 was inadvertently deleted from the final paper and is reproduced here. The on-line version of the paper has been revised.

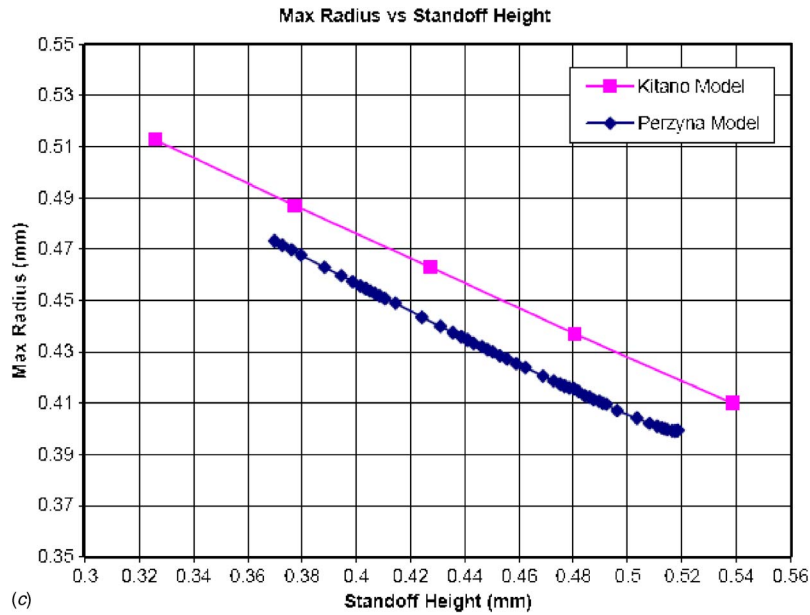


Fig. 6c